



ECH8502 — PNP/NPN Epitaxial Planar Silicon Transistors

Gate Drive Applications

Features

- Composite type, facilitating high-density mounting
- Low collector-to-emitter saturation voltage
 NPN : $V_{CE(sat)}=0.08V(\text{typ.})@I_C=2.5A$
 PNP : $V_{CE(sat)}=-0.12V(\text{typ.})@I_C=-2.5A$
- Mounting height 0.9mm
- Halogen free compliance

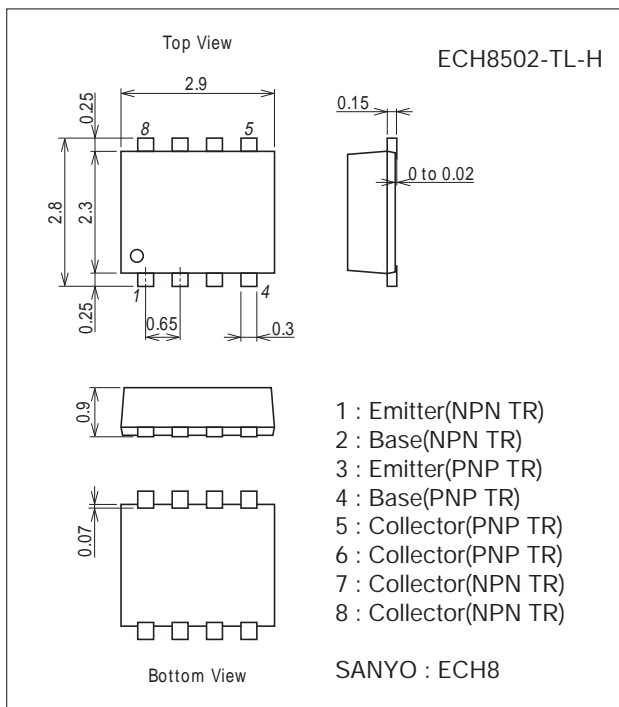
Specifications () : PNP

Absolute Maximum Ratings at $T_a=25^\circ C$

Parameter	Symbol	Conditions	Ratings	Unit
Collector-to-Base Voltage	V_{CBO}		(-50)100	V
Collector-to-Emitter Voltage	V_{CEO}		(-50)	V
Emitter-to-Base Voltage	V_{EBO}		(-6)	V
Collector Current	I_C		(-5)	A
Collector Current (Pulse)	I_{CP}	$PW \leq 1\mu s$, duty cycle $\leq 1\%$	(-30)	A
Base Current	I_B		(-600)	mA
Collector Dissipation	P_C	When mounted on ceramic substrate (900mm ² ×0.8mm) 1unit	1.3	W
Total Dissipation	P_T	When mounted on ceramic substrate (900mm ² ×0.8mm)	1.6	W
Junction Temperature	T_j		150	°C
Storage Temperature	T_{stg}		-55 to +150	°C

Package Dimensions

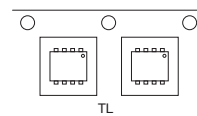
unit : mm (typ)
7011A-007



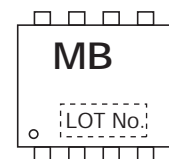
Product & Package Information

- Package : ECH8
- JEITA, JEDEC : -
- Minimum Packing Quantity : 3,000 pcs./reel

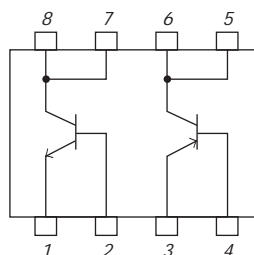
Packing Type : TL



Marking



Electrical Connection



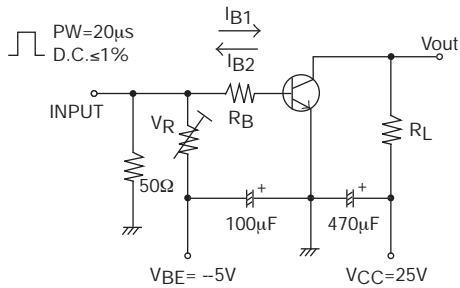
ECH8502

Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Collector Cutoff Current	I_{CBO}	$V_{CB}=(-)50V, I_E=0A$			(-)0.1	μA
Emitter Cutoff Current	I_{EBO}	$V_{EB}=(-)4V, I_C=0A$			(-)0.1	μA
DC Current Gain	h_{FE}	$V_{CE}=(-)2V, I_C=(-)500mA$	200		560	
Gain-Bandwidth Product	f_T	$V_{CE}=(-)10V, I_C=(-)500mA$		(260)290		MHz
Output Capacitance	C_{ob}	$V_{CB}=(-)10V, f=1MHz$		(45)25		pF
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=(-)2.5A, I_B=(-)125mA$		(-120)80	(-200)120	mV
Base-to-Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=(-)2.5A, I_B=(-)125mA$		(-)0.85	(-)1.2	V
Collector-to-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C=(-)10\mu A, I_E=0A$	(-50)100			V
Collector-to-Emitter Breakdown Voltage	$V_{(BR)CEO}$	$I_C=(-)1mA, R_{BE}=\infty$	(-)50			V
Emitter-to-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E=(-)10\mu A, I_C=0A$	(-)6			V
Turn-On Time	t_{on}	See specified Test Circuit.		(30)30		ns
Storage Time	t_{stg}			(180)280		ns
Fall Time	t_f			(20)25		ns

Note : The specifications shown above are for each individual transistor.

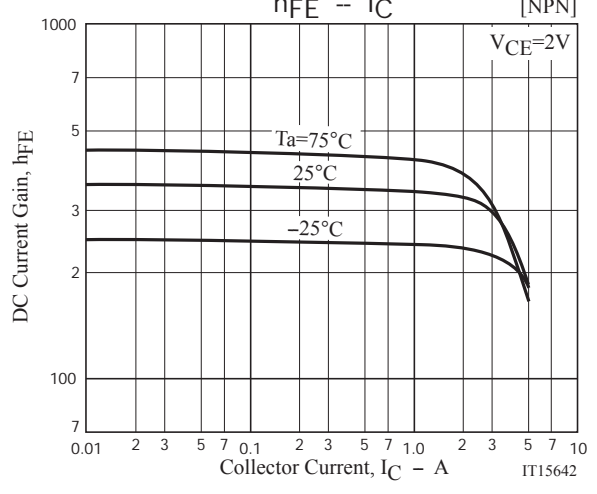
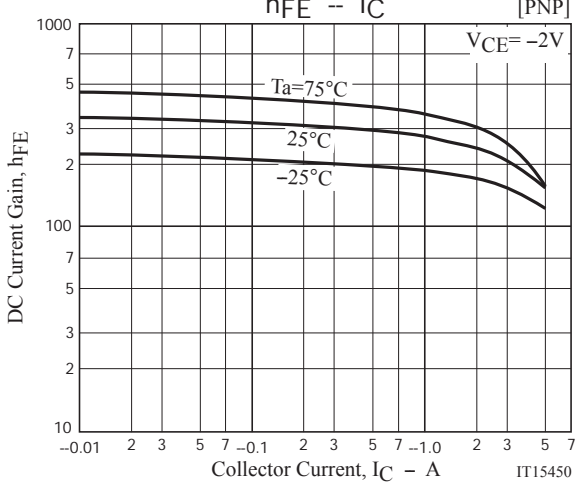
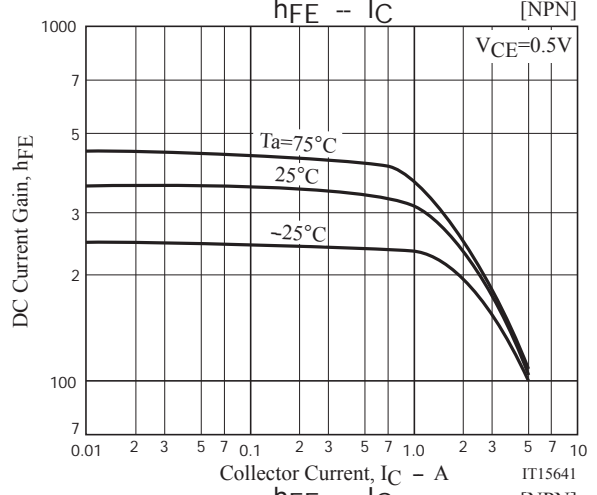
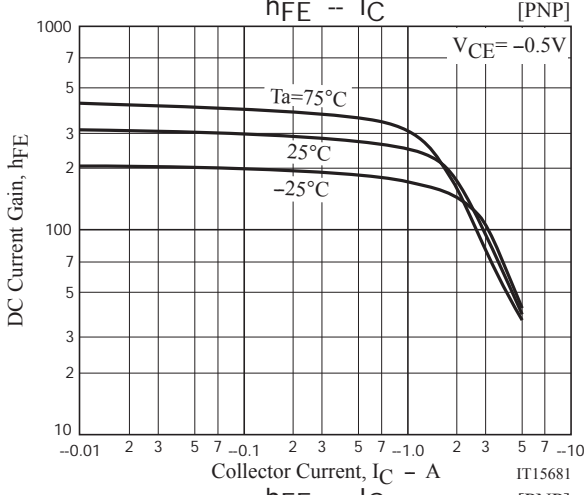
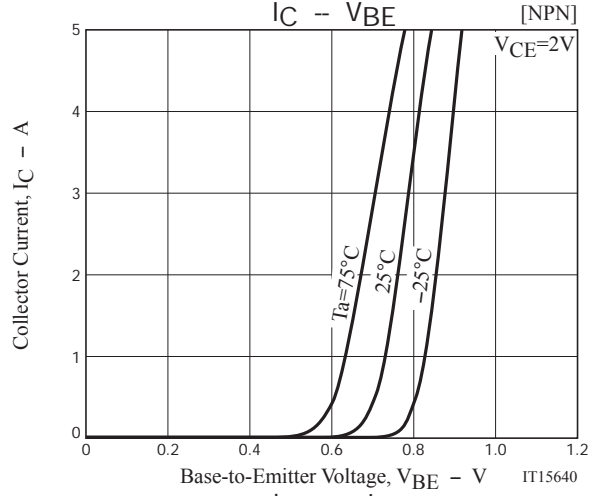
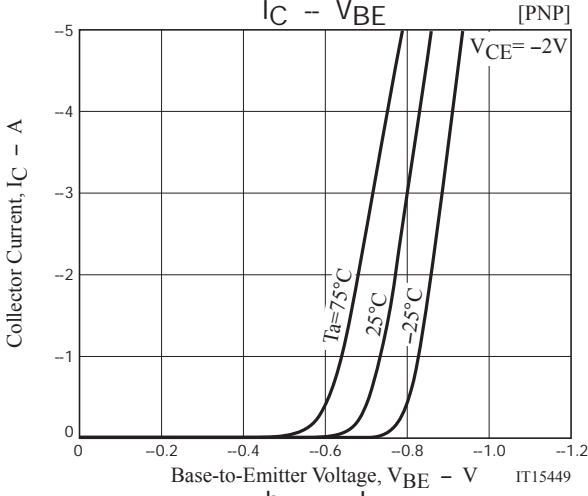
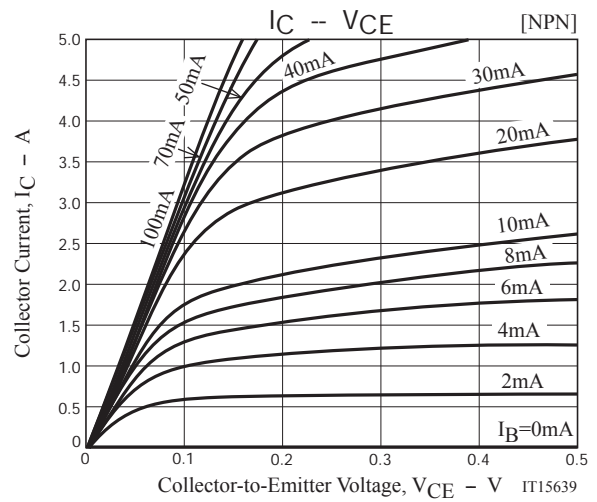
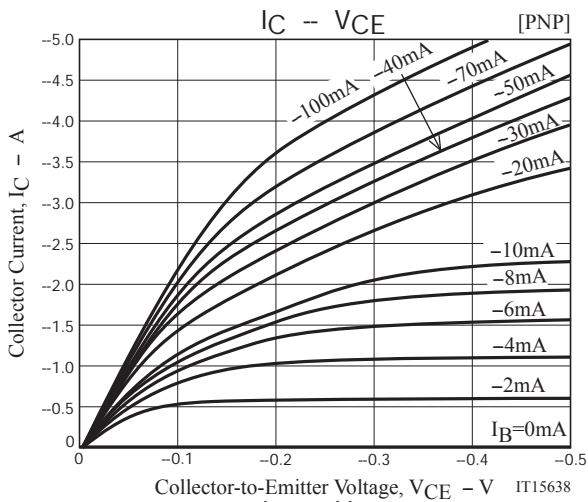
Switching Time Test Circuit

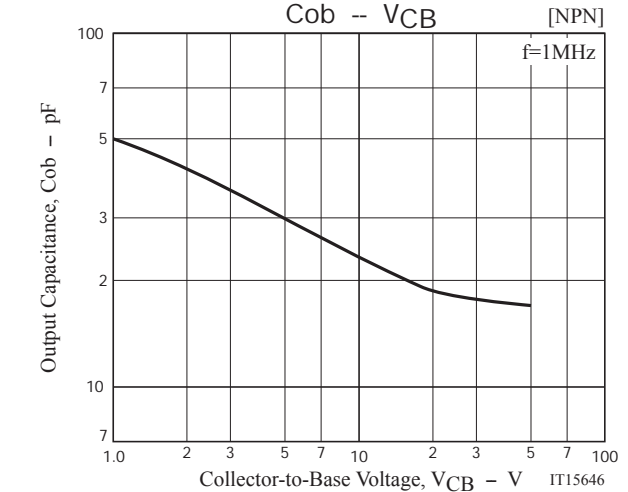
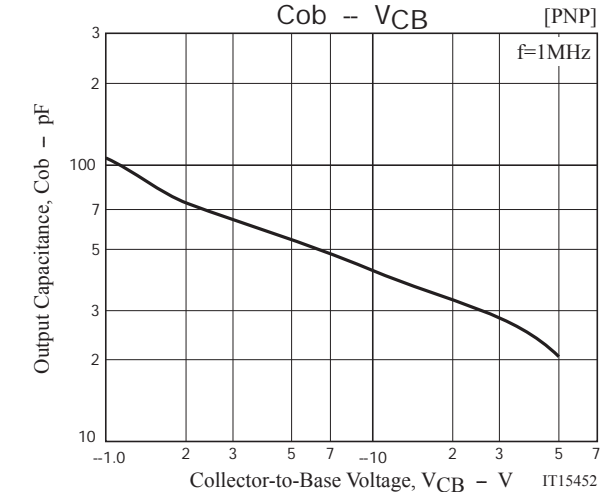
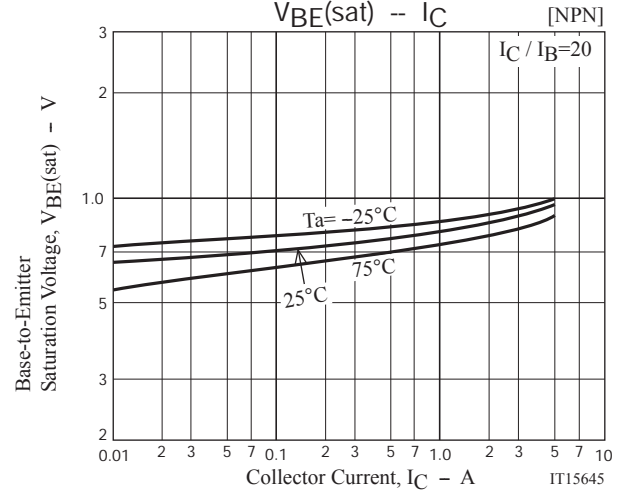
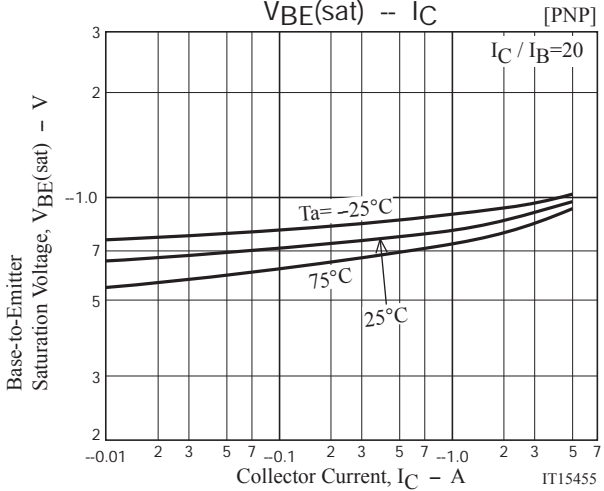
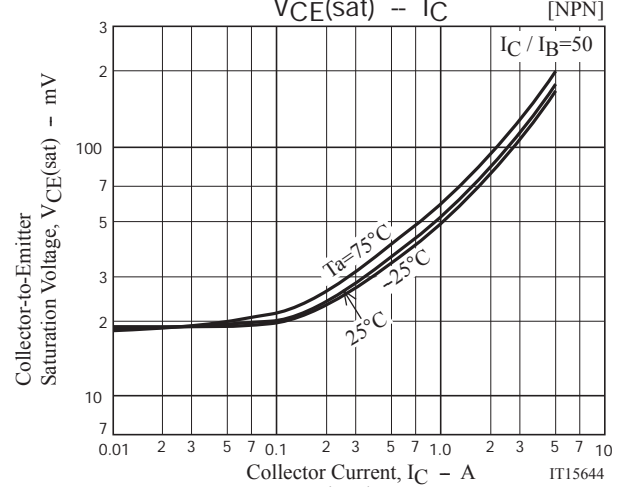
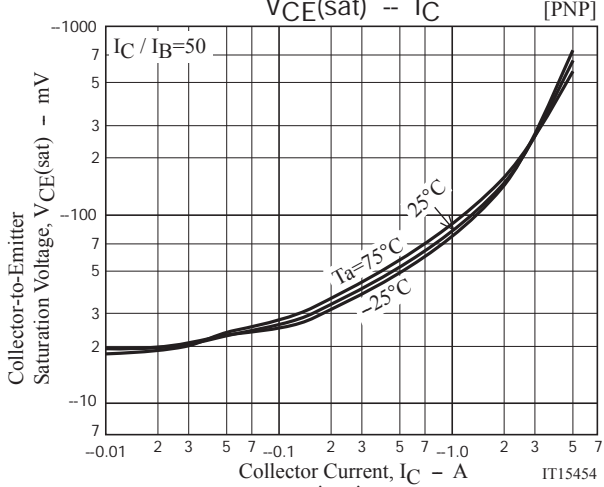
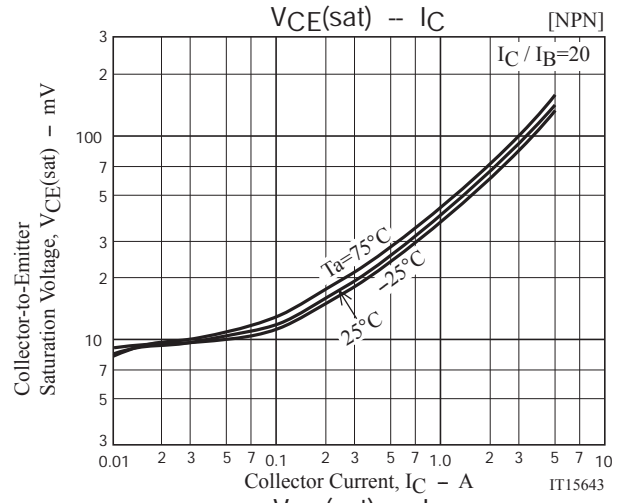
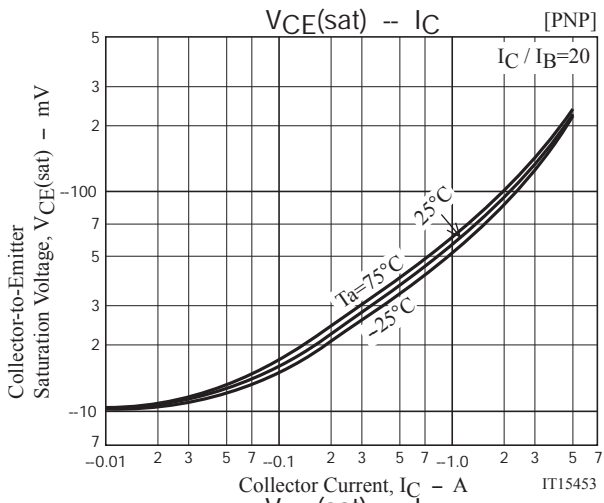


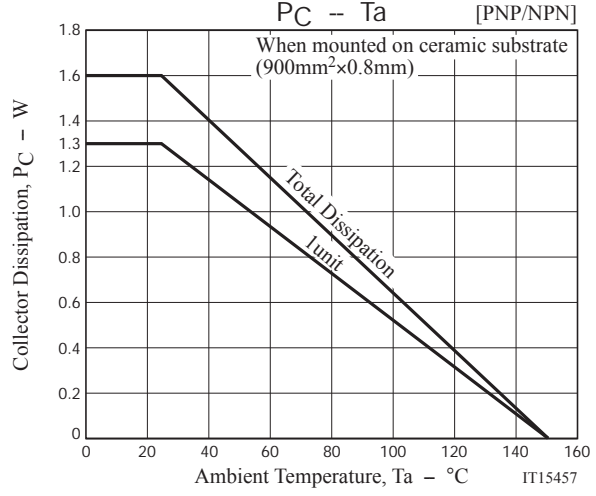
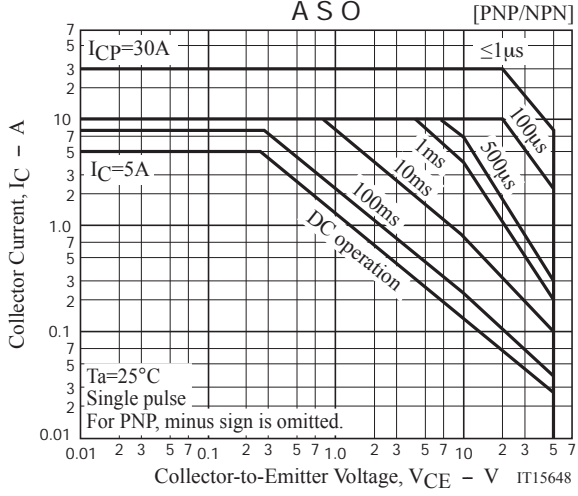
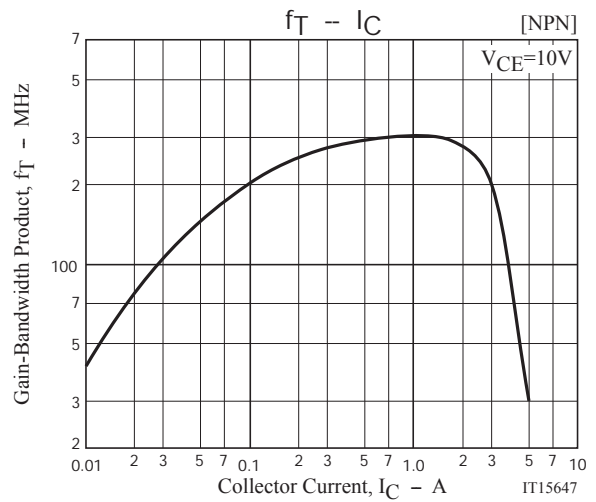
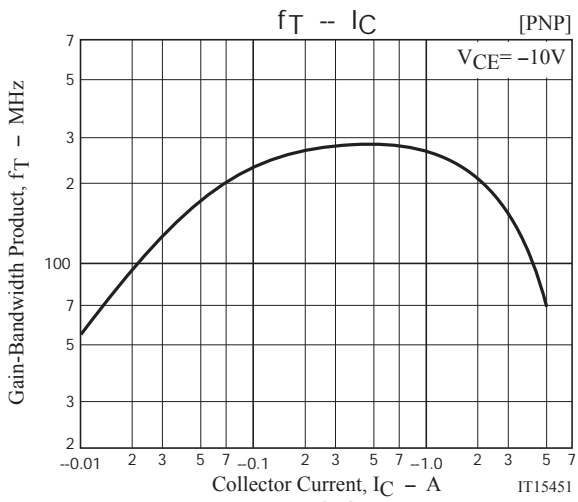
$I_C=20I_{B1}= -20I_{B2}=2.5A$
 (For PNP, the polarity is reversed.)

Ordering Information

Device	Package	Shipping	memo
ECH8502-TL-H	ECH8	3,000pcs./reel	Pb Free and Halogen Free







Embossed Taping Specification

ECH8502-TL-H

1. Packing Format

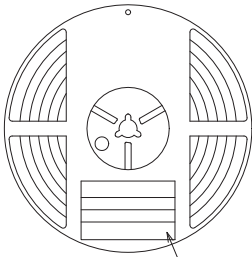
Package Name	Carrier Tape Type	Maximum Number of devices contained (pcs)			Packing format	
		Reel	Inner box	Outer box	Inner BOX (C-1)	Outer BOX (A-7)
ECH8	CPH6	3,000	15,000	90,000	5 reels contained Dimensions:mm (external) 183×72×185	6 inner boxes contained Dimensions:mm (external) 440×195×210

Reel label, Inner box label
(unit :mm)

Outer box label

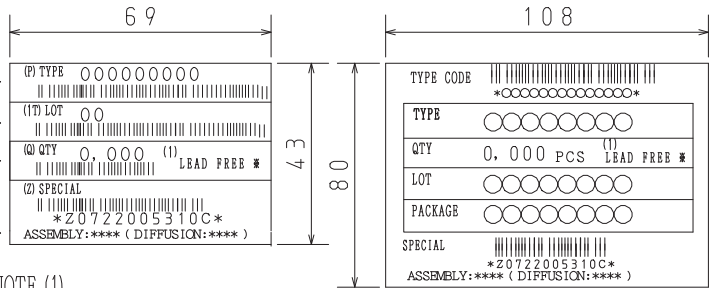
It is a label at the time of factory shipments.
The form of a label may change in physical distribution process.

Packing method



Reel label

Type No.
LOT No.
Quantity
Origin



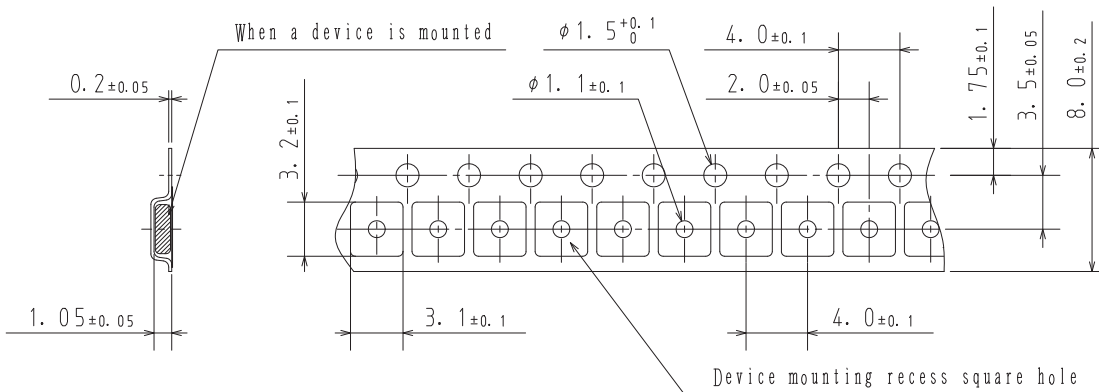
NOTE (1)

The LEAD FREE * description shows that the surface treatment of the terminal is lead free.

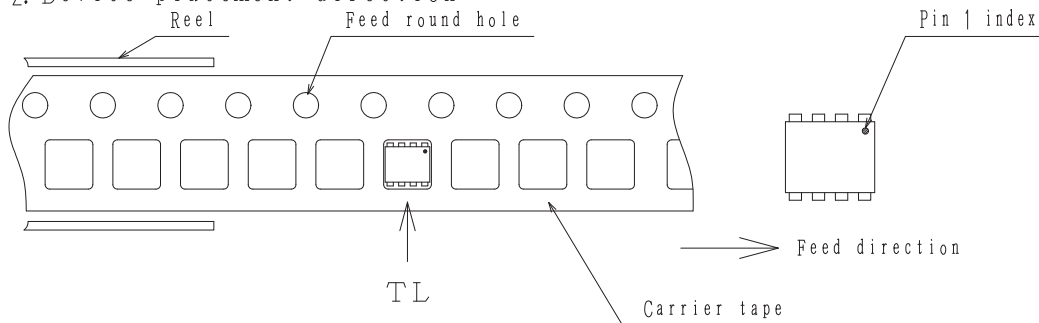
Label	JEITA Phase
LEAD FREE 3	JEITA Phase 3A
LEAD FREE 4	JEITA Phase 3

2. Taping configuration

2-1. Carrier tape size (unit:mm)



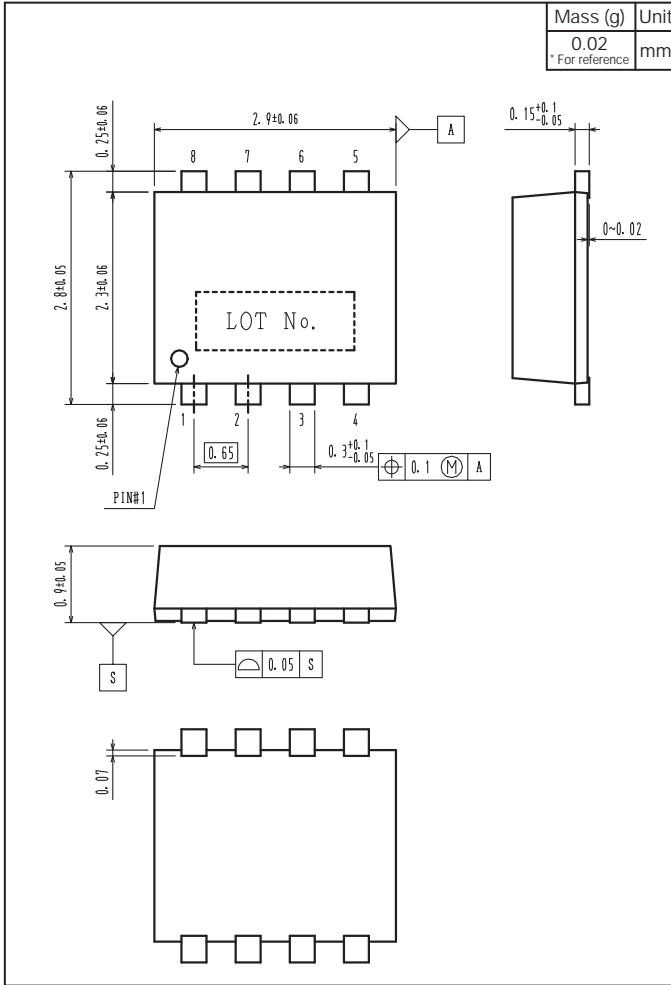
2-2. Device placement direction



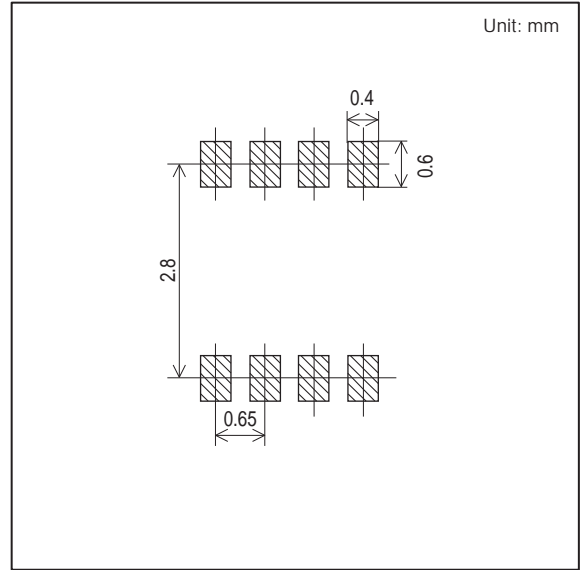
Those with pin 1 index on the feed hole side.....TL

ECH8502

Outline Drawing ECH8502-TL-H



Land Pattern Example



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